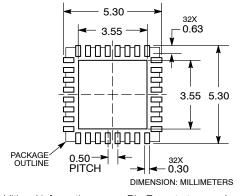


RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

QFN32 5x5, 0.5P

DATE 29 SEP 2015

NOTES:

- 1. DIMENSIONS AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30MM FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
Α	0.80	0.90
A1		0.05
АЗ	0.20 REF	
b	0.18	0.30
D	5.00 BSC	
D2	3.20	3.40
E	5.00 BSC	
E2	3.20	3.40
е	0.50 BSC	
L	0.35	0.45
L1		0.15

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

= Assembly Location

= Wafer Lot WL

= Year = Work Week WW

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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